Appendix I

Amendments to the Specification:

Please replace the paragraph beginning at page 8, line 22, with the following rewritten paragraph:

-- Referring now to FIGS 3 and 4, another embodiment 60 of apparatus for carrying out the method of the present invention is illustrated. Apparatus 60 includes a diode-laser bar including an array of diode-lasers 64. Diode-laser bar 62 is mounted on a heat sink 66. Light 68 from diode-lasers 64 is formed into a line or strip of light 70 by a cylindrical lens 72 and a spherical lens 74. Line of light 70 is formed in a focal plane (not shown) of spherical lens 74. Physical stops 78 are provided for controlling light-intensity distribution along the length of line 70. A detailed description of such a line-of-light projecting apparatus is provided in co-pending application No. 09/522,120, now issued U.S. Patent No. 6,494,371, the complete disclosure of which is hereby incorporated by reference.--

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-8. (Canceled)

9. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) depositing a thermally curable epoxide layer on the electronic component, the epoxide layer including therein at least one light absorbing material; and

(b) directing laser radiation having a wavelength between about 600 and 1000 nm onto the thermally curable epoxide layer for a time period sufficient that the light absorbing material absorbs a portion of the laser radiation and generates heat in the layer, whereby the epoxide layer is cured without external heating and without non-thermal curing.

10. (Original) The method of claim 9, wherein said light absorbing material is carbon black.

11. (Original) The method of claim 9, wherein said light absorbing material is a dye.

12. (Original) The method of claim 9, wherein said light absorbing material is a powdered metal.

13. (Previously Presented) The method of claim 9, wherein said laser radiation has a wavelength of about 808 nm.

14. (Previously Presented) The method of claim 9, wherein said laser radiation is produced by a diode-laser array.

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15. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) providing a diode-laser array for delivering radiation laser radiation having a wavelength between about 600 and 1000 nm;

(b) depositing on the electronic component a thermally curable epoxide layer covering the component, the epoxide layer including therein at least one light absorbing material;

(c) transporting said laser radiation from said diode-laser array, via an optical fiber bundle, to an optical projector for projecting said laser radiation; and

(d) projecting said laser radiation onto said thermally curable epoxide layer for a time period sufficient that the light absorbing material absorbs a portion of the laser radiation and generates heat whereby the epoxide layer is cured without external heating and without non-thermal curing.

16. (Previously Presented) The method of claim 15, wherein said laser radiation has a wavelength of about 808 nm.

17. (Original) The method of claim 15, wherein said at least one light absorbing material is carbon black.

18. (Previously Presented) The method of claim 15, wherein during step (d) said integrated circuit component is held in a fixed relationship to said optical projector and said laser radiation is projected onto said epoxide layer in the form of a spot having a size sufficient to at least cover the electronic component.

19. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) depositing on the electronic component an amount of thermally curable epoxy compound sufficient to form a thermally curable epoxide layer thereof covering the component, the epoxide layer having included therein at least one light absorbing material;

(b) directing laser radiation having a wavelength between about 600 and 1000 nm into an optical projector arranged to project said laser radiation in the form of a line of said laser radiation;

(c) projecting said line of laser radiation onto said thermally curable epoxide layer; and

(d) during step (c), moving the substrate and said integrated circuit with respect to said optical projector such that said thermally curable epoxide layer on the integrated circuit is exposed to said radiation for a time sufficient that said light absorbing material absorbs a portion of the laser radiation and generates heat in the layer whereby the thermally curable epoxide layer is cured without external heating and without non-thermal curing.

20. (Previously Presented) The method of claim 19, wherein said laser radiation is produced by a diode-laser array.

21. (Original) The method of claim 19, wherein said at least one light absorbing material is carbon black.

22. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) depositing on the electronic component a thermally curable liquid epoxide layer including therein at least one light absorbing material; and

(b) irradiating the epoxide layer with laser light generated by a laser diode array and having a wavelength between 600 and ~~100nm~~ 1000nm, the epoxide layer being formulated so that at least 15% of the radiation striking the epoxide layer is absorbed by the at least one light absorbing material in a manner to heat and cure the epoxide layer without external heating and without non-thermal curing.